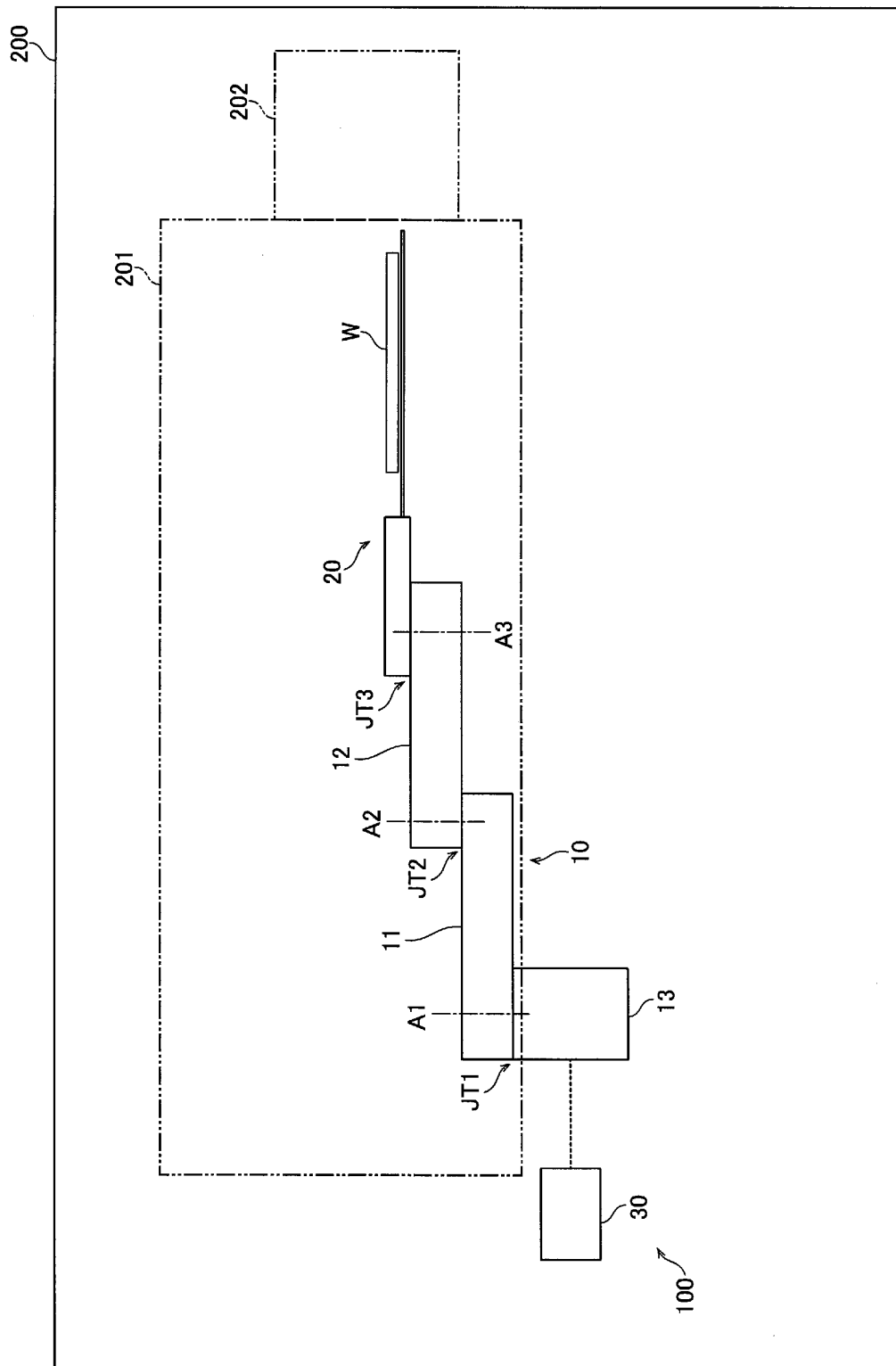


[図1]



100

10

ロボットアーム

駆動機構

モータ

出力軸

エンコーダ

動力伝達部

温度センサ

外気温センサ

エンコーダ温度センサ

制御部

40

50

41

41a

42

43

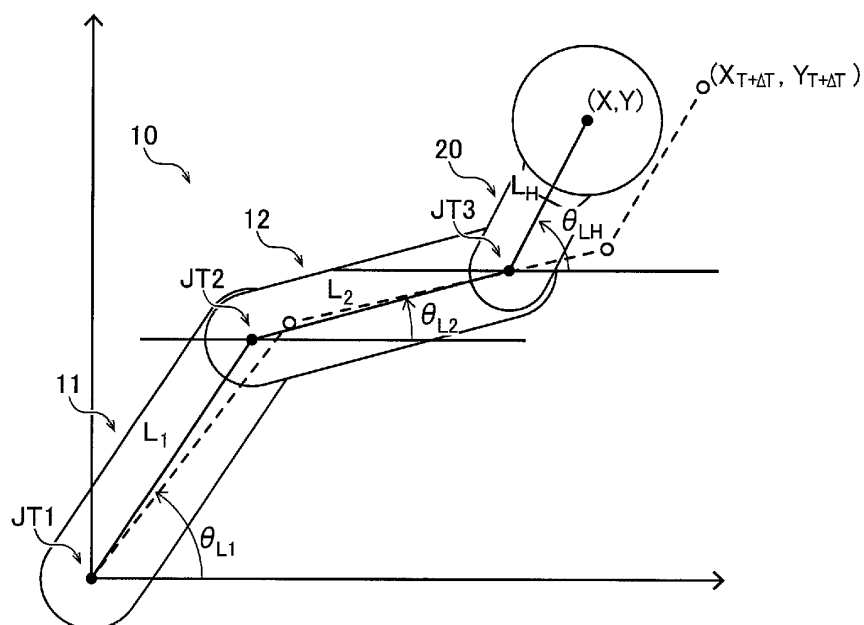
51

52

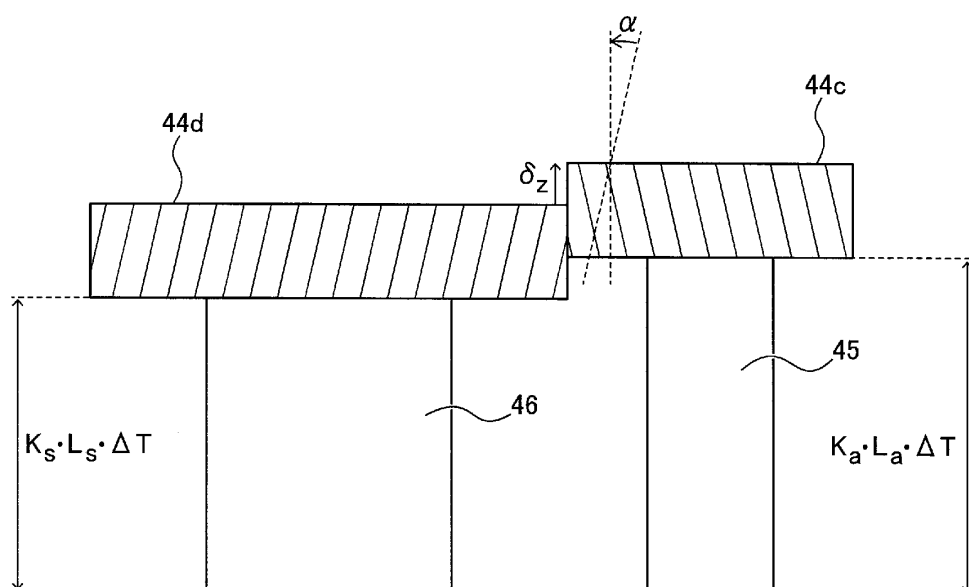
30

A cross-sectional view of a semiconductor device 43. The device includes a substrate 41 with a top layer 42. A central region contains a structure 45, which is flanked by regions 44a and 44b. A layer 46 is positioned above the central region, and a layer 44d is positioned below it. A layer 41a is located between the central region and the right side of the device.

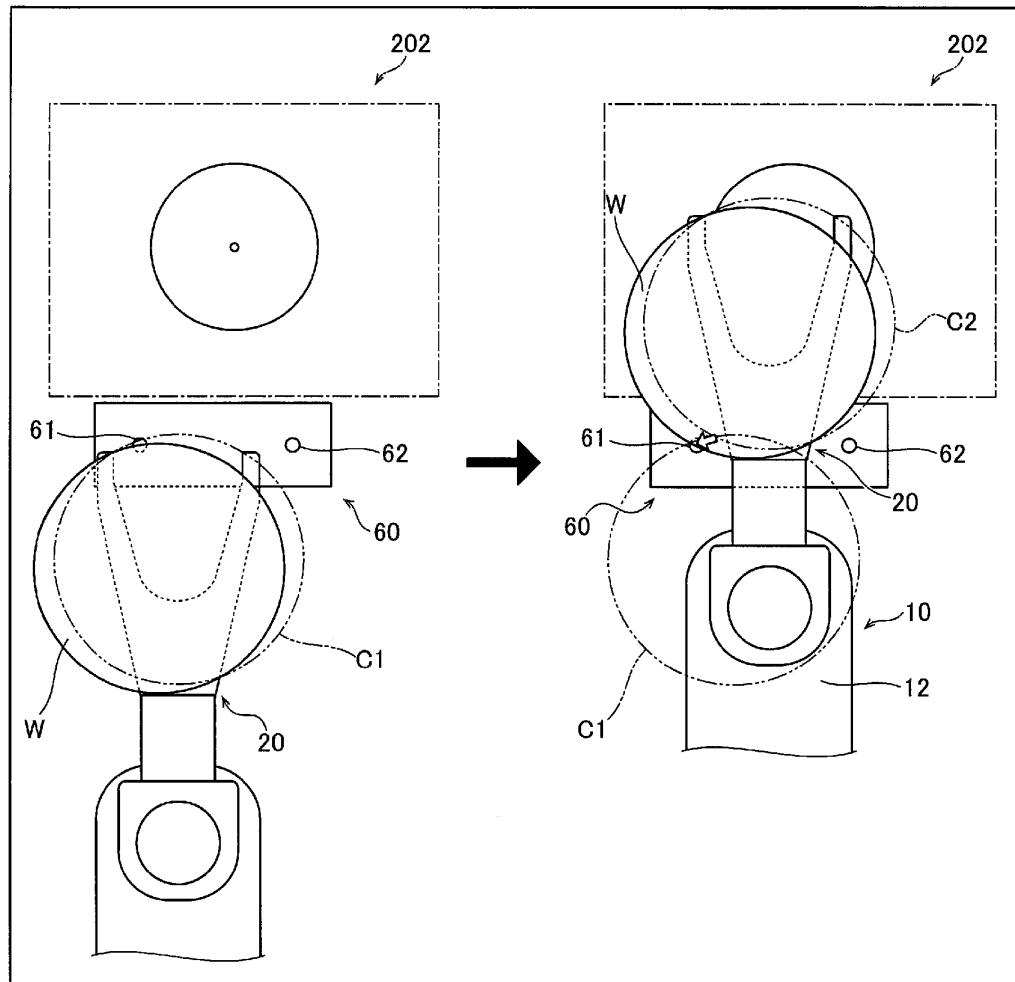
[図4]



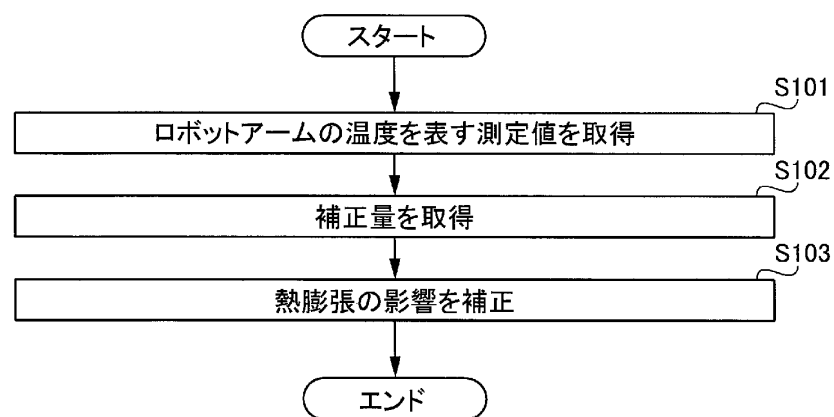
[図5]



[図6]



[図7]



[図8]

